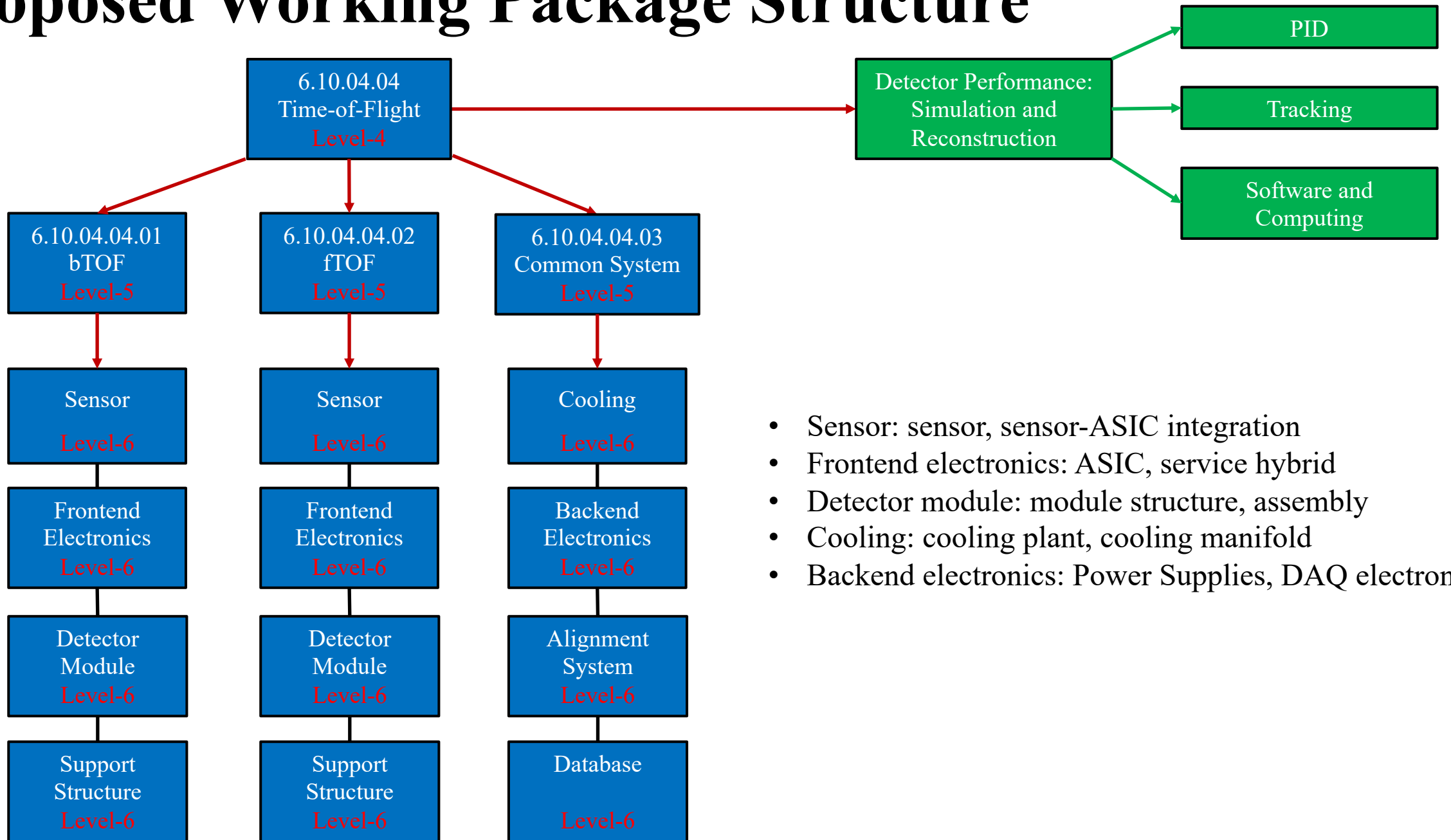


News

- **Incremental Design and Safety Review on ePIC PID detectors conducted on July 5-6**
 - Review [presentations](#); Close-out [slides](#)
- **EIC Project Detector R&D and Design review scheduled in Late Aug/Early Sept**
 - Institutional interests in R&D on page 2
 - FY23 report and FY24 proposals submitted on **July 7**: [eRD109](#) [eRD112](#)
- **ePIC TOF Project Engineering Design**
 - Mechanical engineering request submitted on **June 27**: [Mechanical PED](#)
 - **Low-jitter clock is a part of DAQ PED, TOF RDO in eRD109 FY24 proposal**
- **TOF DSC**
 - Institutional interests in working packages/tasks on page 3-4
 - **Will identify institutional responsibilities and L5/L6 contacts**
- **ePIC Simulation**
 - TOF in tracking – Nicolas: fix the issue with full forward TOF geometry in tracking
 - TOF PID reconstruction – Oskar/Zhenyu: reconstruction, validation plots
 - TOF digitization – Adam/Souvik: charge sharing and detector noise
 - TOF service in simulation – TBD: implement the missing material for mechanical support structure, cooling and cabling
- **EIC User Group Meeting @ Warsaw on July 23-31** <https://indico.cern.ch/event/1238718/>
- **Speaker needed** for TOF talk at New Detectors and Technologies Workshop (hybrid) during RHIC&AGS Annual Users Meeting on **August 2**

Institution	Contact	R&D Interest
Brookhaven National Laboratory	Alessandro/Zhangbu	Sensor prototyping, ASIC testing, Electronics development
Fermi National Accelerator Laboratory	Artur Apresyan	Sensor testing, ASIC prototyping
Los Alamos National Laboratory	Xuan Li	Sensor testing, simulation
Rice University	Wei Li	Sensor testing, Electronics development
Oak Ridge National Laboratory	Oskar Hartbrich	Sensor testing, ASIC testing, Electronics development, Simulation
Ohio State University	Daniel Brandenburg	Electronics testing, Simulation
Purdue University	Andreas Jung	Mechanical structure and cooling system prototyping
University of California, Santa Cruz	Matthew Gignac	Sensor testing, ASIC testing
University of Illinois at Chicago	Zhenyu Ye	Sensor testing, sensor-ASIC integration, ASIC testing, Simulation
Hiroshima University	Kenta Shigaki	Sensor prototyping and testing, Simulation
RIKEN	Yuji Goto	
Shinshu University	Kentaro Kawaide	
University of Tokyo	Taku Gunji	Online data reconstruction
South China Normal University	Shuai Yang	Simulation
Univ of Science and Technology of China	Yanwen Liu	Sensor prototyping, Electronics development, Simulation
Indian Institute of Technology, Mandi	Prabhakar Palni	Sensor testing, Simulation
National Inst. of Sci. Education Research	Ganesh Tambave	Sensor prototyping and testing
National Cheng-Kung University	Yi Yang	Mechanical structure prototyping
National Taiwan University	Rong-Shyang Lu	Sensor prototyping, ASIC testing, Electronics testing

Proposed Working Package Structure



- Sensor: sensor, sensor-ASIC integration
- Frontend electronics: ASIC, service hybrid
- Detector module: module structure, assembly
- Cooling: cooling plant, cooling manifold
- Backend electronics: Power Supplies, DAQ electronics

Institution	Working Group and Tasks
Brookhaven National Laboratory	CS: backend electronics; DP: simulation and reconstruction
Fermi National Accelerator Laboratory	
Los Alamos National Laboratory	FTOF: sensor, module assembly; CS: support structure, cooling system; DP: simulation and reco.
Rice University	BTOF/FTOF: Front-end electronics; CS: backend electronics; DP: simulation and reconstruction
Oak Ridge National Laboratory	BTOF/FTOF: sensor, sensor-ASIC integration, frontend electronics, module assembly
Ohio State University	BTOF/FTOF: module assembly; CS: backend electronics, alignment system; DP: simu. and reco.
Purdue University	BTOF/FTOF: module structure; CS: support structure, cooling system
University of California, Santa Cruz	BTOF: sensor, sensor-ASIC integration, module assembly
University of Illinois at Chicago	BTOF/FTOF: sensor, sensor-ASIC integration, module assembly; DP: simulation and reconstruction
Hiroshima University	BTOF: sensor, module assembly; DP: simulation
RIKEN	
Shinshu University	
University of Tokyo	DP: online reconstruction
South China Normal University	
Univ of Science and Technology of China	
Indian Institute of Technology, Mandi	DP: simulation and reconstruction
National Inst. of Sci. Education Research	
National Cheng-Kung University	BTOF/FTOF: module structure; CS: support structure, cooling system
National Taiwan University	BTOF: sensor-ASIC integration, frontend electronics, module assembly